

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1565-31is8#pbf

(Engineering Calculation)

SOIC

(printed on: 2020-07-11 19:17:21)

**TOTAL MASS (g) : 0.076406**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004473	1000000	58542.6328125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000186	1000000	2434.3684082		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023653	975000	309570.53125		
		Iron (Fe)	7439-89-6	0.000582	24000	7617.21728516		
		Phosphorus (P)	7723-14-0	0.000007	300	91.6160202026		
		Zinc (Zn)	7440-66-6	0.000017	700	222.496047974		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.024259</b>	<b>1000000</b>	<b>317501.84375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001477	1000000	19329.0429688		
		<b>External Plating Total:</b>				<b>0.001477</b>	<b>1000000</b>	<b>19329.0429688</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000194	1000000	2539.07250977		
<b>Internal Plating Total:</b>				<b>0.000194</b>	<b>1000000</b>	<b>2539.07250977</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001208	750000	15810.3066406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000403	250000	5274.46533203		
<b>Die Attach Total:</b>				<b>0.001611</b>	<b>1000000</b>	<b>21084.7714844</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006603	150000	86420.078125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036097	820000	472437.65625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001101	25000	14409.890625		
		Carbon Black (C)	1333-86-4	0.000220	5000	2879.3605957		
		<b>Encapsulation Total:</b>				<b>0.044021</b>	<b>1000000</b>	<b>576146.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000185	1000000	2421.28027344		
					<b>TOTAL MASS (g) :</b>	<b>0.076406</b>		